AMENDMENTS TO THE CLAIMS

Claims 1-36 (Canceled)

Claim 37 (Currently Amended) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface;

a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface;

a pivotal shaft for rotatably supporting said substrate carrier for movement to and from a polishing position, in which polishing position both the first layer and the second layer of the substrate are polished, and in which polishing position said substrate carrier extends outwardly of an outer peripheral portion of said polishing table such that the substrate extends outwardly of the outer peripheral portion of said polishing table;

an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer;

a thickness measurement device for determining an end point of polishing of said first layer, said thickness measurement device being positioned at ~~an~~ the outer peripheral portion of said polishing table so as to be positioned below said substrate carrier, and thus the substrate carried by said substrate carrier, in said polishing position during polishing of the first layer and the second layer of the substrate; and

a second nozzle for providing water toward the surface of the substrate for cleaning the surface after being polished.

Claim 38 (Previously Presented) An apparatus claimed in claim 37, further comprising an actuator for altering a force acting to urge the surface of the substrate against the polishing surface during polishing of the first layer.

Claim 39 (Canceled)

Claim 40 (Currently Amended) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface;

a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface, said substrate carrier having a polishing position in which both the first layer and the second layer of the substrate are polished and in which said substrate carrier extends outwardly of an outer peripheral portion of said polishing table such that the substrate extends outwardly of the outer peripheral portion of said polishing table;

an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer; and

a thickness measurement device ~~for determining an end point of polishing of the first layer, said thickness measurement device being~~ positioned at an outer peripheral portion of said polishing table so as to be positioned below said substrate carrier, and thus the substrate carried by said substrate carrier, in said polishing position during polishing of the first layer and the second layer of the substrate.

Claim 41 (Previously Presented) An apparatus claimed in claim 40, further comprising a second nozzle for providing water toward the surface of the substrate for cleaning the surface of the substrate after being polished.

Claims 42-43 (Canceled)

Claim 44 (New) An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface the diameter of which is substantially 1.5 times the diameter of the substrate;

a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface;

a pivotal shaft for rotatably supporting said substrate carrier for movement to and from a polishing position, in which polishing position both the first layer and the second layer of the substrate are polished, and in which polishing position said substrate carrier extends outwardly of an outer peripheral portion of said polishing table such that the substrate extends outwardly of the outer peripheral portion of said polishing table;

an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a first polishing liquid while polishing the first layer, and for supplying a second polishing liquid while polishing the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer;

a thickness measurement device for determining an end point of polishing of said first layer, said thickness measurement device being positioned at ~~an~~ the outer peripheral portion of said polishing table so as to be positioned below said substrate carrier, and thus the substrate carried by said substrate carrier, in said polishing position during polishing of the first layer and the second layer of the substrate; and

a second nozzle for providing water toward the surface of the substrate for cleaning the surface after being polished.

Claim 45 (New) An apparatus claimed in claim 44, wherein said attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.

Claim 46 (New) An apparatus claimed in claim 45, wherein the temperature of said polishing liquid is controlled so as to keep constant level.

Claim 47 (New) An apparatus claimed in claim 37, wherein the diameter of said polishing table is substantially 1.5 times the diameter of the substrate.

Claim 48 (New) An apparatus claimed in claim 40, wherein the diameter of said polishing table is substantially 1.5 times the diameter of the substrate.